



Technical Query

Primary Contact Information

Viasystems Technologies Corp.,
L.L.C., a member of TTM
Technologies Group
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To: _____
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Phone: _____

Secondary Contact Information

To: _____
Email: _____
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Date: 5/24/2018

Viasystems			
Contacts	Primary	Secondary	Field Application Engineer
Customer Service:	Taylor Williams		
Phone:			
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Technical Support:	Yogeswaran Perinpanayagam		
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e-mail:	yperin@ttm.com		

PLEASE, COPY ALL ABOVE ON ALL CORRESPONDENCES

Customer Name:	DEBRON INDUSTRIAL ELECTRONICS	
Customer P/N:	40-00643-00LF	
Rev #:	-	
Site Tooling P/N:	181875	
Viasystems P/N:		
Order Type:	Manufacturing Build	

Site : TO

Data

Issue #	Status	Issue	Proposed Resolution	Customer Response	Links
1	On Hold- Not Started	Stack-up attached for your approval.			
2	On Hold- Not Started	Geber data attached for your approval			
3	On Hold- Not Started	lpc netlist not found. We will extract from gerber data.			
4	On Hold- Not Started	We have added 50mil dot-pattern thieving spaced at 75mil c/c keeping 200mil away from features. Please find attached data and approve.			

5	On Hold- Not Started	Customer provided big copper pads for 106.3 and 118.1mil depth drills in both outer layers, We will do secondary drilling for these non-plated holes.			
6	On Hold- Not Started	artwork received for plug via from top side. The vias required plugging are exposed from both sides. Can we remove sm clearance for these vias from both sides and plug them?			
7	On Hold- Not Started	There is no info on score, array dimension. we will score rails using 30 degree blade, web 0.015 +/-5mil. We have added tooling holes and fiducial at the location specified in otl layer.			